

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

Chen, et al.

Serial No.: 10/810,965

Filed: March 26, 2004

For: Novel Method to Improve Bump Reliability for
Flip Chip Device

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) Confirmation No.: 9818

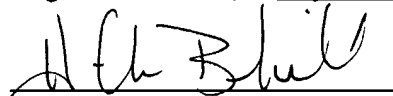
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) Examiner: Trinh, Hoa B.

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) Group Art Unit: 2814

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) TKHR Docket: 252016-2530
) Top-Team: 0503-A30731US

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Mail Stop Amendment; Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on May 19, 2005.


Signature – Hui Chin Barnhill

AMENDMENT AND RESPONSE TO OFFICE ACTION

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

The Office Action mailed January 19, 2005 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.